

09/759,018

Patent
IBM Docket No. FIS920000310US1

In the specification:

Replace the paragraph on page 6, lines 7-12, with the following:

Referring now to the drawings, Figure 1 is a schematic drawing of a composition for containing metal ions in electronic devices according to a preferred embodiment of the present invention. As shown in Figure 1, the inventive composition 100 includes a very high molecular weight insoluble and immobile particle 110, such as a polymer which serves as an insoluble and immobile phase, and a chelating agent 120 which is permanently bonded to the immobile particle 110.

In the claims:

Claims 1-3 Withdrawn.

4. (Currently amended) An electronic device having an integrated circuit with a composition for containing metal ions, said composition comprising:

a matrix material;

a polymer which serves as an insoluble and immobile particle phase in said matrix material;

and

a chelating agent which is bonded to said insoluble and immobile particle phase.

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5. (Currently amended) The electronic device according to claim 4, wherein said composition is contained within a scratch coat covering an active surface of said integrated circuit.

6. (Original) The electronic device according to claim 4, further comprising:

a package, to which said integrated circuit is bonded.

7. (Currently amended) The electronic device according to claim 6, wherein said composition is contained within an encapsulant which is deposited over substantially an entire surface of said integrated circuit and between said integrated circuit and said package.

8. (Currently amended) The electronic device according to claim 6, wherein said composition is contained within an underfill which is deposited between said integrated circuit and said package.

9. (Currently amended) The electronic device according to claim 6, wherein said package comprises an organic package and wherein said composition is contained within said organic package.

10. (Original) The electronic device according to claim 6, further comprising:

a printed circuit board to which said package is bonded.

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11. (Currently amended) The electronic device according to claim 10, wherein said composition is contained within an underfill which is deposited between said package and said printed circuit board.

12. (Currently amended) The electronic device according to claim 10, wherein said composition is contained within said printed circuit board.

13. (Currently amended) The electronic device according to claim 10, wherein said composition is contained within a conformal coating which is deposited over said integrated circuit, said package and said printed board.

Claims 14-37 Withdrawn.